



## Materials Declaration Form

<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

\*: Required Field

<b>Supplier Information</b>			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2018-02-09</b>
<b>Contact Name *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Authorized Representative *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Rossana Bonaccorso</b>	<b>Representative Title</b>	<b>ADG MD Champion</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STU7NM60N	TSIK*M260B8F	A	998G	2018-02-09
	Amount	UoM	Unit type	ST ECOPACK Grade
	310	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	6.1-6.5-2.3	3	Through-hole	
Comment	IPAK TO-251			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015			
Query			Response
1 - Product(s) meets EU RoHS requirement without any exemptions			FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)			FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions			FALSE
Exemption Id.	Description		
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)		

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	2.37	Die / Leadframe	7635
Lead	3.53	Soft solder	11371

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TSIK*M26088F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.930	mg	supplier	die	Silicon (Si)	7440-21-3		3.773	mg	960051	12171
				supplier	metallization	Aluminium (Al)	7429-90-5		0.075	mg	19084	242
				supplier	Passivation	Silicon Nitride	12033-89-5		0.018	mg	4580	58
				supplier	Passivation	Silicon Oxide	7631-86-9		0.027	mg	6870	87
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	509	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.026	mg	6616	84
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.009	mg	2290	29
Leadframe	M-004 Copper and its alloys	184.074	mg	supplier	alloy	Copper (Cu)	7440-50-8		181.496	mg	985995	585471
				supplier	alloy	Iron (Fe)	7439-89-6		0.182	mg	988	587
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.055	mg	299	177
				supplier	metallization	Nickel (Ni)	7440-02-0		2.341	mg	12718	7552
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high me	3.525	mg	955026	11371
Soft solder	Solder	3.691	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.525	mg	955026	11371
				supplier	solder	Silver (Ag)	7440-22-4		0.092	mg	24925	297
				supplier	solder	Tin (Sn)	7440-31-5		0.074	mg	20049	239
Bonding wires	M-011 Other inorganic materials	0.648	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.648	mg	1000000	2090
Encapsulation	M-011 Other inorganic materials	113.954	mg	supplier	mold compound	Silica, vitreous	60676-86-0		99.140	mg	870000	319806
				supplier	mold compound	Epoxy resin	25068-38-6		11.395	mg	99996	36758
				supplier	mold compound	Phenol resin	29690-82-2		2.849	mg	25001	9190
				supplier	mold compound	Carbon Black	1333-86-4		0.570	mg	5003	1840
Connections coating	Solder	3.703	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.703	mg	1000000	11945